



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2021-03-19
Company Unique ID	NL 008751171B01		
Authorized Representative *	Antonella Lanzaafme	Representative Title	AMS Material Declaration Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STUSB4500QTR	1YND*VB0GABJ	A	Z6HA	2021-03-19
Amount	UoM	Unit type	ST ECOPACK Grade	
44.0	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	



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Package Designator	Size	Nbr of instances	Shape	
QFN	4 x 4	24	no lead	
Comment	ND VFQFPN 4x4x1.0 24 PITCH 0.5			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020	
Query	Response
1 - Product(s) meets EU ELV requirement without any exemptions	true
2 - Product(s) meets EU ELV requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 18th December 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			true
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Homogeneous Material (mg)	Application - Homogeneous Material	ppm in Homogeneous Material
Responsible metals sourcing				
Query				Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.				false
The following metals are present is the component :				

China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	
Query	Response

Material Composition Declaration						Mfr Item Name	1YND*VB0GABJ		44.0000		1000000.0	1000003.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	4.446	mg	supplier	die	Silicon(Si)	7440-21-3		4.444	mg	999550	101000
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.001	mg	225	23
				supplier	metallisation	Copper(Cu)	7440-50-8		0.001	mg	225	23
Leadframe	M-004 Copper and its alloys	17.691	mg	supplier	alloy	Copper (Cu)	7440-50-8		16.904	mg	0	384182
				supplier	alloy	Iron (Fe)	7439-89-6		0.397	mg	0	9023
				supplier	alloy	Phosphorus (P)	7723-14-0		0.099	mg	0	2250
				supplier	alloy	Zinc (Zn)	7440-66-6		0.022	mg	0	500
				supplier	metallization	Nickel (Ni)	7440-02-0		0.254	mg	0	5773
				supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	0	114
				supplier	metallization	Gold (Au)	7440-57-5		0.005	mg	0	114
Die attach	M-015 Other organic materials	0.772	mg	supplier	metallization	Silver (Ag)	7440-22-4		0.005	mg	0	114
				supplier	glue	Silver	7440-22-4		0.681	mg	0	15477
				supplier	glue	2-Propionic acid, methyl ester reaction pro	Proprietary		0.068	mg	0	1545
				supplier	glue	2-Propenoic acid, 2-methyl-, 2-[[[2,3,3a,4,7	68586-19-6		0.020	mg	0	455
Bonding wires	M-011 Other inorganic materials	0.048	mg	supplier	glue	Bis(alpha.,alpha.-Dimethylbenzyl) peroxide	80-43-3		0.001	mg	0	23
				supplier	glue	2-(3,4-Epoxy cyclohexyl)ethyltrimethoxysilane	3388-04-3		0.002	mg	0	45
				supplier	wire	Copper (Cu)	7440-50-8		0.048	mg	0	1091
				supplier	glue	Epoxy resin	29690-82-2		0.625	mg	0	14205
Encapsulation	M-015 Other organic materials	20.856	mg	supplier	glue	Phenol resin	25068-38-6		0.625	mg	0	14205
				supplier	glue	Silica (Amorphous) A	60676-86-0		16.924	mg	0	384636
				supplier	glue	Silica (Amorphous) B	7631-86-9		2.816	mg	0	64000